



SURFACE MOUNT SWITCHING DIODE

Features

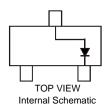
- Fast Switching Speed: Maximum of 4ns
- Low Forward Voltage: Maximum of 0.715V at 1mA
- Low Capacitance: Maximum of 2pF
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208 (3)
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagram
- Weight: 0.008 grams (approximate)







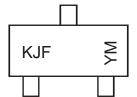
Ordering Information (Note 4 & 5)

Part Number	Case	Packaging
BAL99-7-F	SOT23	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.
- 7. To plackaging detail, go to an Website at https://www.nidector.com/battas/poly.pdi.
 7. Product manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

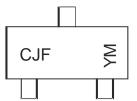
Marking Information



K = SAT (Shanghai Assembly / Test site) JF = Product Type Marking Code YM = Date Code Marking

Y = Year ex: Z = 2012

M = Month ex: 9 = September



C = CAT (Chengdu Assembly / Test site) JF = Product Type Marking Code YM = Date Code Marking

July 2012

Y = Year ex: Z = 2012M = Month ex: 9 = September

Date Code Key

Year	1998	1999	2000	2001	2002		2012	2013	2014	2015	2016	2017	2018	2019	2020
Code	J	K	L	М	N		Z	Α	В	С	D	Е	F	G	Н
Month	Jan	F	eb	Mar	Apr	May	J	un	Jul	Aug	Sep	Oc	et	Nov	Dec
Code	1		2	3	4	5		6	7	8	9	С)	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		V_{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _R WM V _R	75	V
RMS Reverse Voltage		$V_{R(RMS)}$	53	V
Forward Continuous Current (Note 6)		I _{FM}	300	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs @ t = 1.0s	I _{FSM}	2.0 1.0	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	350	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ heta JA}$	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

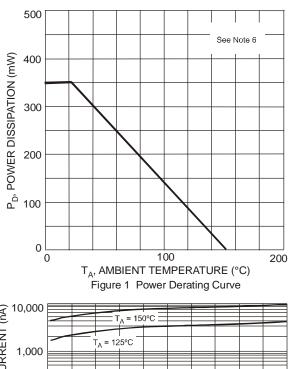
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

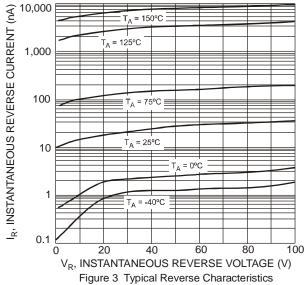
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	75		>	$I_R = 100 \mu A$
Forward Voltage	VF		0.715 0.855 1.0 1.25	V	I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA
Reverse Current (Note 7)	I _R	_	2.5 50 30 25	μΑ μΑ μΑ nA	$V_R = 75V$ $V_R = 75V$, $T_J = +150^{\circ}C$ $V_R = 25V$, $T_J = +150^{\circ}C$ $V_R = 20V$
Total Capacitance	Ст		2.0	pF	$V_R = 0, f = 1.0MHz$
Reverse Recovery Time	t _{rr}	_	4.0	ns	$\begin{aligned} I_F &= I_R = 10 \text{mA}, \\ I_{rr} &= 0.1 \text{ x } I_R, \ R_L = 100 \Omega \end{aligned}$

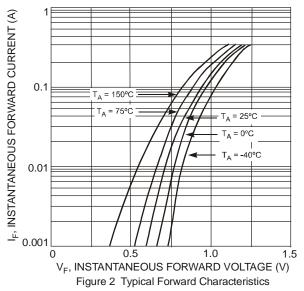
Notes:

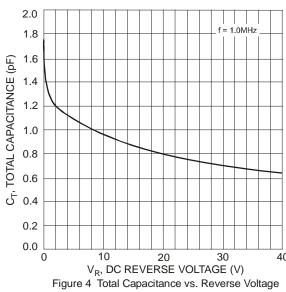
- 6. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 7. Short duration pulse test used to minimize self-heating effect.



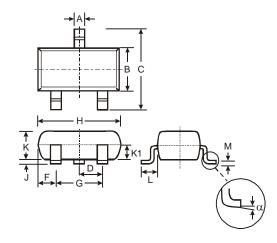








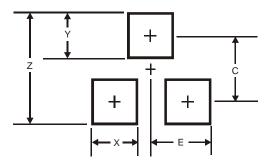
Package Outline Dimensions



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Η	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.903	1.10	1.00				
K1	-	-	0.400				
L	0.45	0.61	0.55				
М	0.085	0.18	0.11				
α	0°	8°	-				
All Dimensions in mm							



Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35

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